

Features

- For surface mounted applications in order to optimize board space
- Pb-free plated
- Peak Power is 240W@1ms
- ESD Rating of Class X (> 15 kV) (IEC6100-4-2)
- Response Time is Typically <1 ns
- Low profile package
- Typical IR less than 1μA above 10V
- Low inductance
- Excellent clamping capability
- AEC-Q101



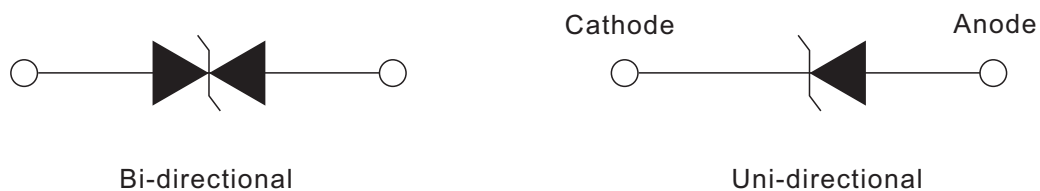
Applications

- I/O interface
- AC/DC power supply
- Low frequency signal transmission line (RS232, RS485, etc.)

Mechanical Characteristics

- **Case:** JEDEC SOD-123FL. Molded plastic over glass passivated junction
- **Terminal:** Solderable per MIL-STD-750, Method 2026
- **Polarity:** Color band denoted positive end (cathode) except Bidirectional

Functional Diagram



Maximum Ratings And Characteristics

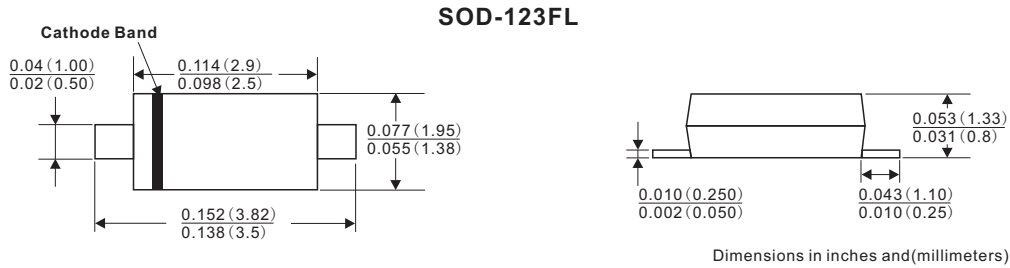
Ratings at 25°C ambient temperature unless otherwise specified.

RATING	SYMBOL	VALUE	UNITS
Peak Pulse Power Dissipation on 10/1000μs waveform	P _{PPM}	240	Watts
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load, (JEDEC Method) (Note 2,3)	I _{FSM}	20	Amps
Operating junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes :

1. Non-repetitive current pulse , per Fig. 3 and derated above T_A = 25°C per Fig. 2 .
2. Mounted on 5.0mm x 5.0mm (0.03mm thick) Copper Pads to each terminal
3. 8.3ms single half sine-wave , or equivalent square wave, Duty cycle = 4 pulses per minutes maximum.

Dimensions (SOD-123FL)



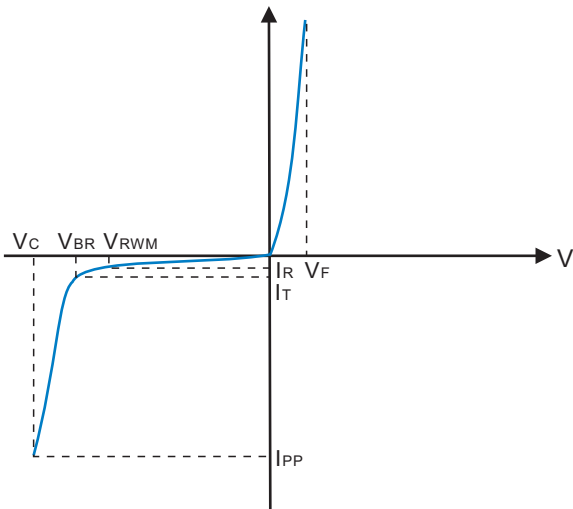
Electrical Characteristics

TSA Part Number		Device Marking Code		Reverse Stand-Off Voltage	Breakdown Voltage @IT		Test Current	Maximum Clamping Voltage @IPP	Peak Pulse Current	Reverse Leakage @VRWM
UNI-Polar	BI-Polar	UNI	BI	VRWM(V)	VBR(V)Min.	VBR(V)Max.	IT(mA)	Vc(V)	IPP(A)	IR(μA)
TSA6.0U	TSA6.0B	AG	WG	6.0	6.67	7.37	10	10.3	23.3	100
TSA8.0U	TSA8.0B	AR	WR	8.0	8.89	9.83	1	13.6	17.7	25
TSA12U	TSA12B	BE	XE	12.0	13.30	14.70	1	19.9	12.1	2
TSA15U	TSA15B	BM	XM	15.0	16.70	18.50	1	24.4	9.8	1
TSA16U	TSA16B	BP	XP	16.0	17.80	19.70	1	26.0	9.2	1
TSA18U	TSA18B	BT	XT	18.0	20.00	22.10	1	29.2	8.2	1
TSA20U	TSA20B	BV	XV	20.0	22.22	24.50	1	32.4	7.4	1
TSA22U	TSA22B	BX	XY	22.0	24.40	26.90	1	35.5	6.8	1
TSA24U	TSA24B	BZ	XZ	24.0	26.70	29.50	1	38.9	6.2	1
TSA26U	TSA26B	CE	YE	26.0	28.90	31.90	1	42.1	5.7	1
TSA28U	TSA28B	CG	YG	28.0	31.10	34.40	1	45.4	5.3	1
TSA30U	TSA30B	CK	YK	30.0	33.30	36.80	1	48.4	5.0	1
TSA33U	TSA33B	CM	YM	33.0	36.70	40.60	1	53.3	4.5	1
TSA36U	TSA36B	CP	YP	36.0	40.00	44.20	1	58.1	4.1	1
TSA40U	TSA40B	CR	YR	40.0	44.40	49.10	1	64.5	3.7	1
TSA51U	TSA51B	CZ	YZ	51.0	56.70	62.70	1	82.4	2.9	1
TSA58U	TSA58B	RG	ZG	58.0	64.40	71.20	1	93.6	2.6	1
TSA60U	TSA60B	RK	ZK	60.0	66.70	73.70	1	96.8	2.5	1
TSA150U	TSA150B	SM	VM	150.0	167.00	185.00	1	243.0	1.0	1
TSA170U	TSA170B	SR	VR	170.0	189.00	209.00	1	275.0	0.9	1

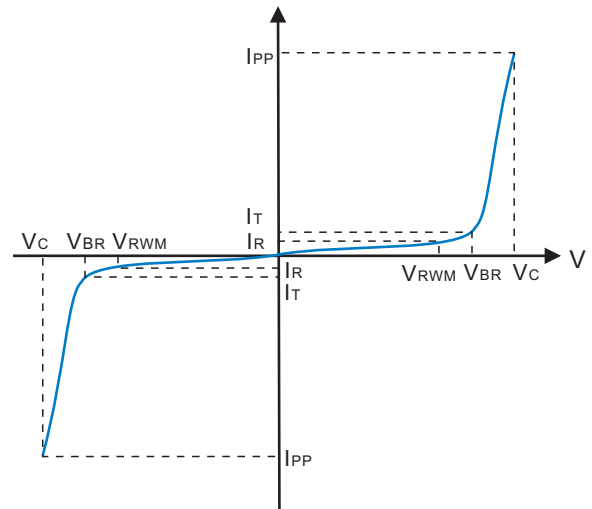
For bidirectional type having VRWM of 10 volts and less, the IR limit is double.

I-V Curve Characteristics

Uni-directional



Bi-directional



Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Peak Pulse Power Rating Curve

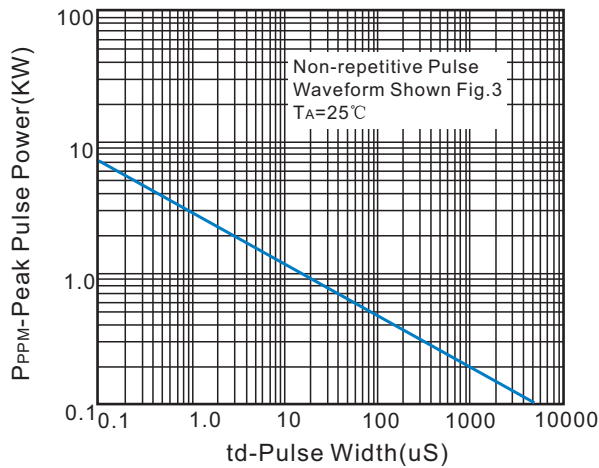


Fig.2 Pulse Derating Curve

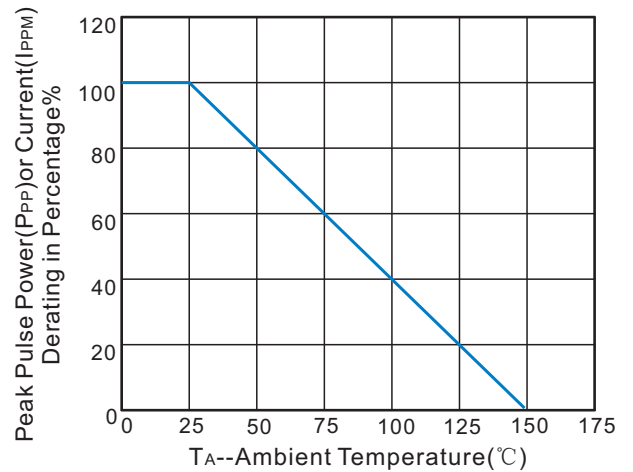


Fig.3 Pulse Waverform

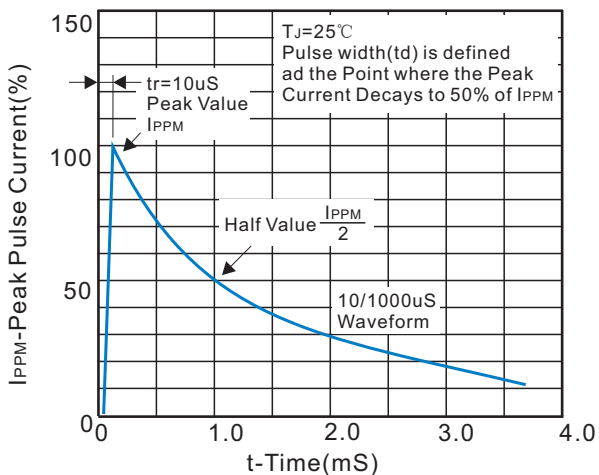
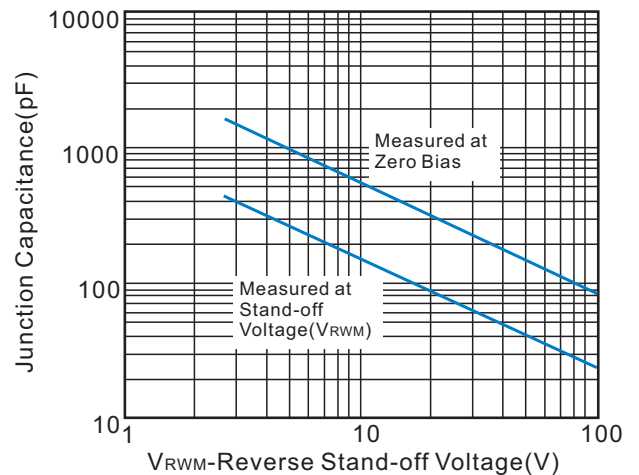
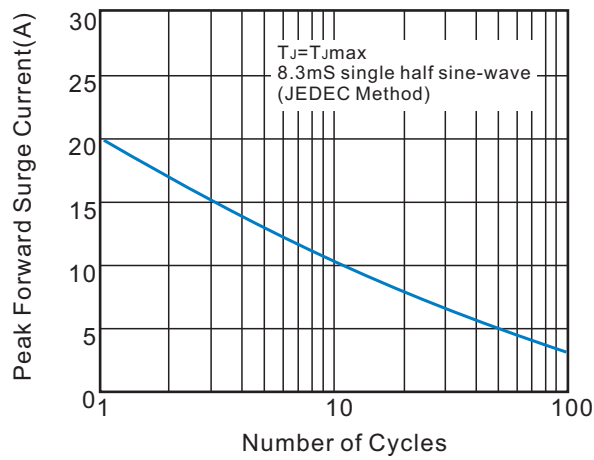


Fig.4 Typical Junction Capacitance



Ratings And Characteristic Curves($T_A=25^{\circ}\text{C}$ Unless otherwise noted)

Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

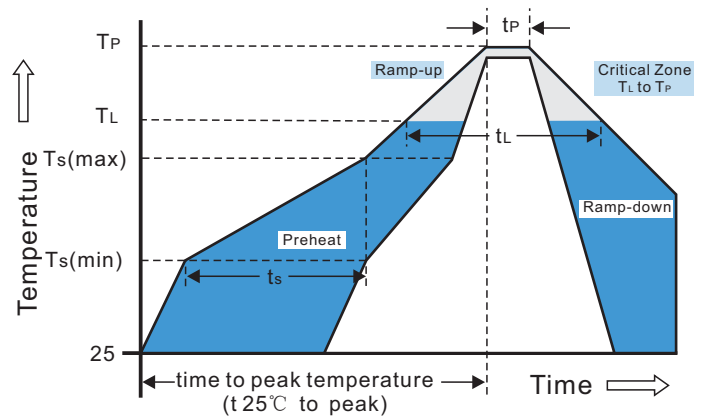


Recommended Soldering Conditions

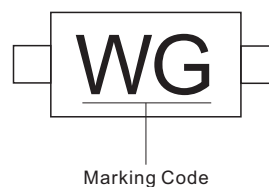
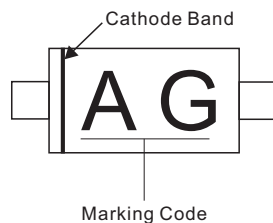
Recommended Conditions

Reflow Condition		Pb-Free assembly (see Fig.1)
Pre Heat	-Temperature Min($T_{s(min)}$)	+150 $^{\circ}\text{C}$
	-Temperature Max($T_{s(max)}$)	+200 $^{\circ}\text{C}$
	-Time(Min to Max)(t_s)	60-180secs
Average ramp up rate (Liquidus Temp(T_L) to peak)		3 $^{\circ}\text{C}/\text{sec. Max.}$
$T_{s(max)}$ to T_L -Ramp-up Rate		3 $^{\circ}\text{C}/\text{sec. Max.}$
Reflow	-Temperature(T_L)(Liquidus)	+217 $^{\circ}\text{C}$
	-Temperature(t_L)	60-150secs
Peak Temp(T_P)		+260(+0/-5) $^{\circ}\text{C}$
Time within 5 $^{\circ}\text{C}$ of actual Peak Temp(t_P)		30 secs. Max.
Ramp-down Rate		6 $^{\circ}\text{C}/\text{sec. Max.}$
Time 25 $^{\circ}\text{C}$ to Peak Temp(T_P)		8 min. Max.
Do not exceed		+260 $^{\circ}\text{C}$

Reflow Soldering

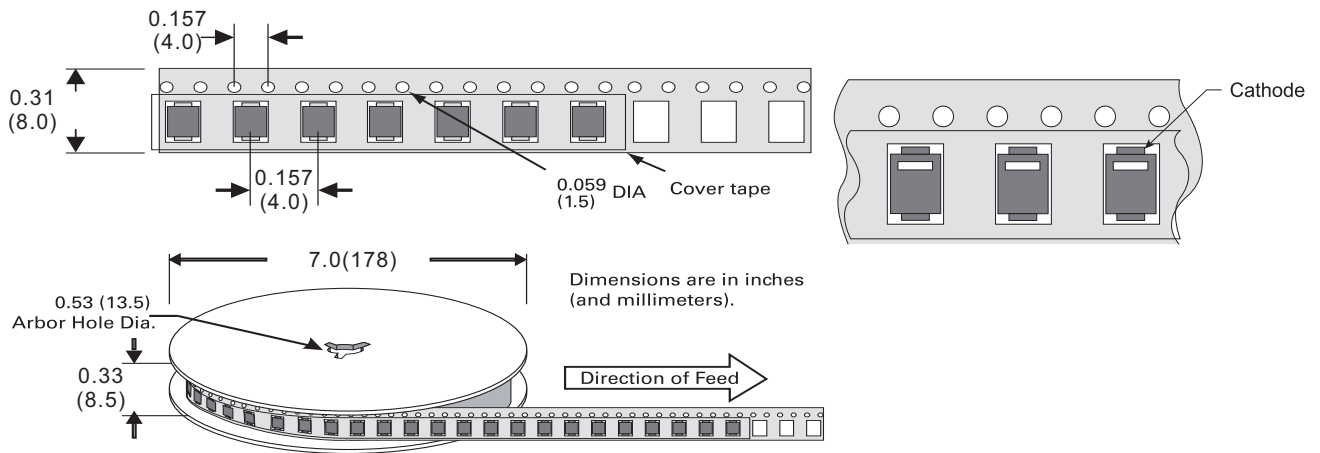


Marking Code



Packing Options And Reel Specification-SOD-123FL

Symbol	Ea Per Reel	REEL DIA (mm)	Industry Standard
TSA***	3000	178	EIARS-481



单击下面可查看定价，库存，交付和生命周期等信息

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